

PCN Number:	20260901002.1	PCN Issued	September 02, 2026
Qualification of alternate lead finish material for select devices		Sample request deadline:	November 01, 2026
		Estimated 1st ship date:	December 01, 2026
Sample requests received after November 01, 2026 will not be supported.			

Change type(s)
Assembly Material

PCN Details

Description of Change:		
Texas Instruments is pleased to announce the qualification This PCN is to inform of an alternate lead finish material set for the list of devices in the product affected sections below. Device will remain on current Assembly sites.		
What	Current	Additional
Lead finish	NiPdAu	Matte Sn
Upon expiry of this PCN, there will be a transition period where TI will combine lead free solutions in a single <u>standard part number</u>. For example; <u>DP83822IFRHBT</u> – can ship with both Matte Sn and NiPdAu. Example: - Customer order for 7500 units of DP83822IFRHBT with 2500 units SPQ (Standard Pack Quantity per Reel). - TI can satisfy the above order in one of the following ways. I. 3 Reels of NiPdAu finish. II. 3 Reels of Matte Sn finish III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish. IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish. Qual details are provided in the Qual Data Section.		
Reason for Change:	Continuity of supply	

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Physical aspects of the device have changed Request the Supporting Data Packet (SDP) for more details on the changes.								
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. <table><tr><td>RoHS</td><td>REACH</td><td>Green Status</td><td>IEC 62474</td></tr><tr><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td></tr></table>	RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change
RoHS	REACH	Green Status	IEC 62474						
☒ No Change	☒ No Change	☒ No Change	☒ No Change						

Changes to product identification resulting from this PCN:

Sample product shipping label (not actual product label)

G4 = NiPdAu
G3 = Matte Sn

TEXAS
INSTRUMENTS
MADE IN: Malaysia
2DC: 20:
MSL 2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CS0: SHE (21L) CC0: USA
(22L) AS0: MLA (23L) AC0: MYS

Products Affected:

Please refer to the PCN email sent for the list of devices affected.

Qualification Report
Approve Date 23-MAY -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS51604DSGR-S	Qual Device: ADS8168IRHBR	Qual Device: TPS7A0512PDQNR	Qual Device: INA190A3IRSWR-S	QBS Reference: TUSB546A- DCIRNQR	QBS Reference: ADS8168IRHBR	QBS Reference: DRV8353HRTAR	QBS Reference: INA190A3IRSWR-S
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	3/231/0	3/231/0	3/231/0	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0	3/231/0	-	3/231/0	3/231/0	-	3/231/0
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/5/0	1/5/0	1/5/0	-	1/22/0	1/22/0	-	1/5/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	3/60/0	3/60/0	3/60/0	-	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device TPS51604DSGR-S is qualified at MSL1 260C

Qual Device ADS8168IRHBR is qualified at MSL2 260C

Qual Device TPS7A0512PDQNR is qualified at MSL1 260C

Qual Device INA190A3IRSWR-S is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-010

Qualification Report

Approve Date 30-MAY -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPD1E10B06DPYR	Qual Device: INA190A3IRSWR-S
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	1/5/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device TPD1E10B06DPYR is qualified at MSL1 260C

Qual Device INA190A3IRSWR-S is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-076

Qualification Report

Approve Date 24-January-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: CC1354P106T0RGZR	Qual Device: OPA2673IRGVR	Qual Device: TMUX7208RUMR	Qual Device: SN003020RTER
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0	3/231/0	3/231/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	1/22/0	1/22/0	1/22/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device CC1354P106T0RGZR is qualified at MSL3 260C

Qual Device OPA2673IRGVR is qualified at MSL2 260C

Qual Device TMUX7208RUMR is qualified at MSL1 260C

Qual Device SN003020RTER is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-078

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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